

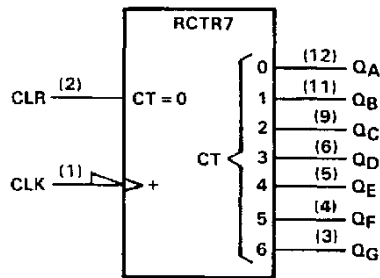
- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

description

The 'HC4024 is an asynchronous 7-stage binary counter designed with an input pulse-shaping circuit. The outputs of all stages are available externally. A high clear signal asynchronously clears the counter and resets all outputs low. The count is advanced on the high-to-low transition of the clock pulse. Applications include time-delay circuits, counter controls, and frequency-dividing circuits.

The SN54HC4024 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74HC4024 is characterized for operation from -40°C to 85°C.

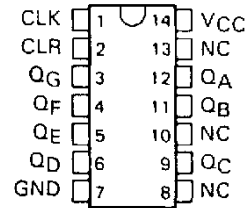
logic symbol†



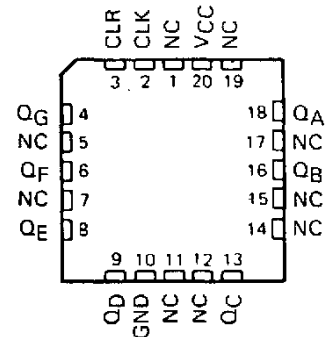
†This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

SN54HC4024 . . . J PACKAGE
SN74HC4024 . . . D OR N PACKAGE
(TOP VIEW)



SN54HC4024 . . . FK PACKAGE
(TOP VIEW)



NC—No internal connection

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

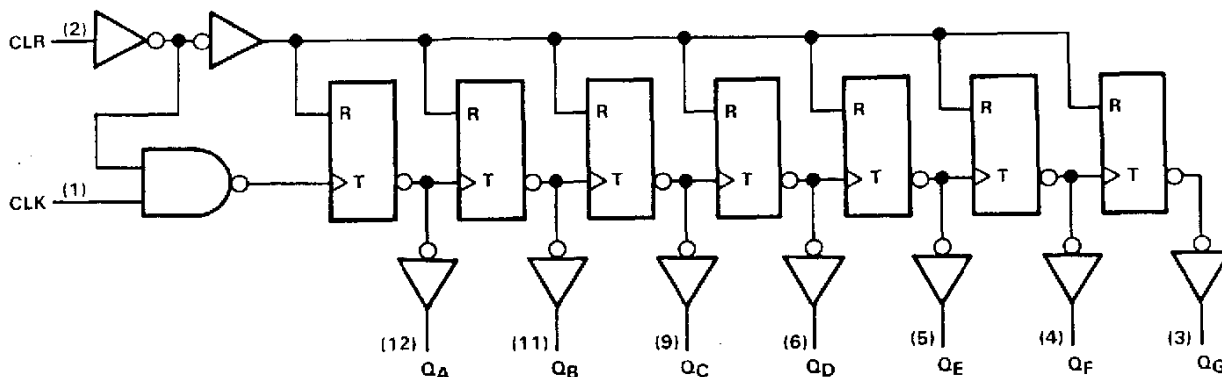


POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

Copyright © 1989, Texas Instruments Incorporated

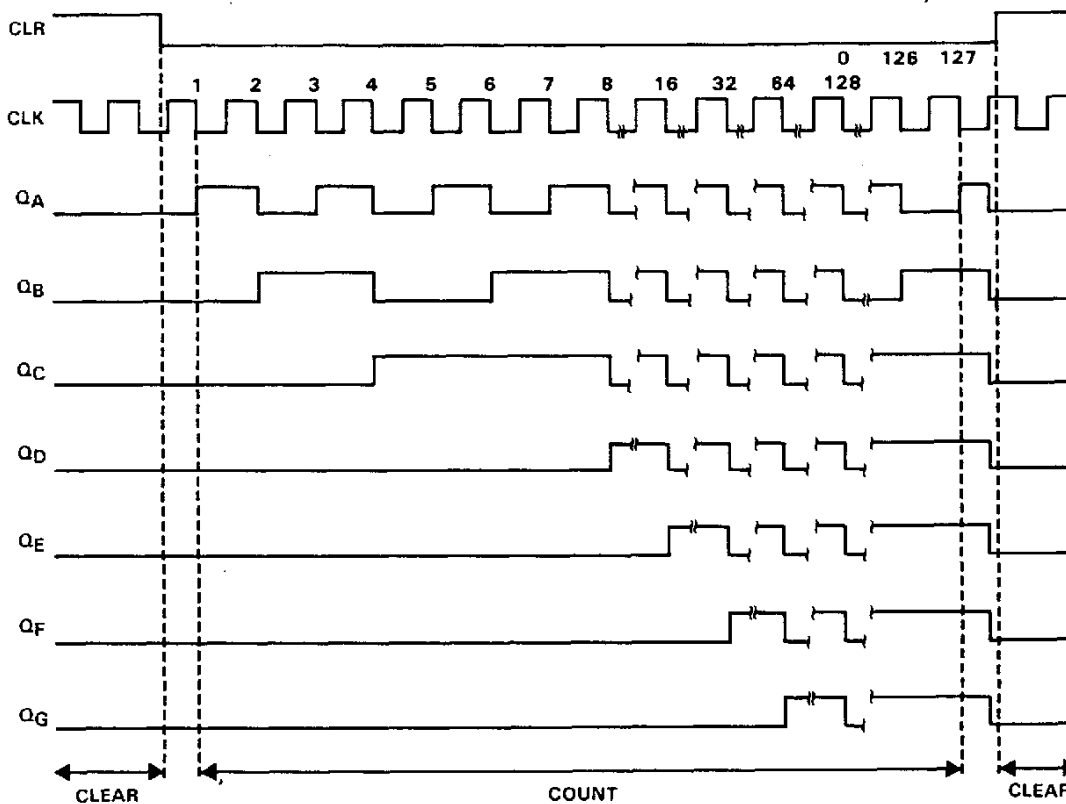
SN54HC4024, SN74HC4024 ASYNCHRONOUS 7-BIT BINARY COUNTERS

logic diagram (positive logic)



Pin numbers shown are for D, J, and N packages.

typical clear and count sequence



TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN54HC4024, SN74HC4024 ASYNCHRONOUS 7-BIT BINARY COUNTERS

absolute maximum ratings over operating free-air temperature range†

Supply voltage, V_{CC}	-0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND pins	± 50 mA
Lead temperature 1,6 mm (1/16 in) from case for 60 s: FK or J package	300°C
Lead temperature 1,6 mm (1/16 in) from case for 10 s: D or N package	260°C
Storage temperature range	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54HC4024			SN74HC4024			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	2	5	6	2	5	6	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V		1.5	$V_{CC} = 2$ V		1.5	V
		$V_{CC} = 4.5$ V		3.15	$V_{CC} = 4.5$ V		3.15	
		$V_{CC} = 6$ V		4.2	$V_{CC} = 6$ V		4.2	
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V		0	$V_{CC} = 2$ V		0	V
		$V_{CC} = 4.5$ V		0	$V_{CC} = 4.5$ V		0	
		$V_{CC} = 6$ V		0	$V_{CC} = 6$ V		0	
V_I	Input voltage	0			V_{CC}			V
V_O	Output voltage	0			V_{CC}			V
t_t	Input transition (rise and fall) times	$V_{CC} = 2$ V		0	$V_{CC} = 2$ V		0	ns
		$V_{CC} = 4.5$ V		0	$V_{CC} = 4.5$ V		0	
		$V_{CC} = 6$ V		0	$V_{CC} = 6$ V		0	
T_A	Operating free-air temperature	-55			125			°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25^\circ\text{C}$		SN54HC4024		SN74HC4024		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	
V_{OH}	$V_I = V_{IH}$ or V_{IL} , $I_{OH} = -20 \mu\text{A}$	2 V	1.9	1.998		1.9		1.9	V
		4.5 V	4.4	4.499		4.4		4.4	
		6 V	5.9	5.999		5.9		5.9	
	$V_I = V_{IH}$ or V_{IL} , $I_{OH} = -4$ mA	4.5 V	3.98	4.30		3.7		3.84	
	$V_I = V_{IH}$ or V_{IL} , $I_{OH} = -5.2$ mA	6 V	5.48	5.80		5.2		5.34	
V_{OL}	$V_I = V_{IH}$ or V_{IL} , $I_{OL} = 20 \mu\text{A}$	2 V		0.002	0.1		0.1		V
		4.5 V		0.001	0.1		0.1		
		6 V		0.001	0.1		0.1		
	$V_I = V_{IH}$ or V_{IL} , $I_{OL} = 4$ mA	4.5 V		0.17	0.26		0.4		
	$V_I = V_{IH}$ or V_{IL} , $I_{OL} = 5.2$ mA	6 V		0.15	0.26		0.4		0.33
I_I	$V_I = V_{CC}$ or 0	6 V		± 0.1	± 100		± 1000		nA
I_{CC}	$V_I = V_{CC}$ or 0, $I_O = 0$	6 V			8		160		μA
C_i		2 to 6 V		3	10		10		pF



SN54HC4024, SN74HC4024
ASYNCHRONOUS 7-BIT BINARY COUNTERS

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V _{CC}	T _A = 25 °C		SN54HC4024		SN74HC4024		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	2 V	0	5.5	0	3.7	0	4.3	MHz
		4.5 V	0	28	0	19	0	22	
		6 V	0	33	0	22	0	25	
t _w	Pulse duration	CLK high or low	2 V	90		135		115	ns
			4.5 V	18		27		23	
			6 V	15		23		20	
	CLR high	2 V	80		120		100	ns	
		4.5 V	16		24		20		
		6 V	14		20		17		
t _{su}	Setup time, CLR low before CLK↓	2 V	80		120		100	ns	
		4.5 V	16		24		20		
		6 V	14		20		17		

switching characteristics over recommended operating free-air temperature range (unless otherwise noted), C_L = 50 pF (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25 °C			SN54HC4024		SN74HC4024		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}		Q _A	2 V	5.5	10		3.7		4.3	MHz	
			4.5 V	28	50		19		22		
			6 V	33	60		22		26		
t _{pd}	CLK	Q _A	2 V		56	120		180		150	ns
			4.5 V		16	24		36		30	
			6 V		12	20		31		26	
t _{PHL}	CLR	Any	2 V		61	130		195		165	ns
			4.5 V		17	26		39		32	
			6 V		13	22		33		28	
t _t		Q _A	2 V		28	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

C _{pd}	Power dissipation capacitance	No load, T _A = 25 °C	40 pF typ
-----------------	-------------------------------	---------------------------------	-----------

Note 1: Load circuits and voltage waveforms are shown in Section 1.



POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
86012012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	86012012A SNJ54HC 4024FK	Samples
8601201CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8601201CA SNJ54HC4024J	Samples
SN54HC4024J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54HC4024J	Samples
SN74HC4024N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	-40 to 85		
SNJ54HC4024FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	86012012A SNJ54HC 4024FK	Samples
SNJ54HC4024J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8601201CA SNJ54HC4024J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "--" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54HC4024, SN74HC4024 :

- Catalog: [SN74HC4024](#)

- Military: [SN54HC4024](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Military - QML certified for Military and Defense Applications

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com